11 -	29-2005
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	e record the attached documents or the new address(es) below.
1. Name of conveying party(ies)/Execution Date(s): TOMOKO TERAKADO (11/02/2005), CHIEKO KUSAKABE (11/11/2005), AND KANAKO NAKAMURA (11/09/2005)	Name and address of receiving party(ies) Name: SONY CORPORATION
	Internal Address:
Execution Date(s): in parentheses after inventor name Additional name(s) of conveying party(ics) attached? Yes X No 3. Nature of Conveyance:	Street Address: 7-35, Kitashinagawa 6-chome Shinagawa-Ku
X Assignment Merger	1
Security Agreement Change of Name	City:Tokyo
Government Interest Assignment	State:
Executive Order 9424, Confirmatory License	Country:JAPANzip:141-0001
Other	Additional name(s) & address(es) Yes X No
Additional numbers attached 5. Name and address to whom correspondence	6. Total number of applications and
concerning document should be mailed:	patents involved:
Name: Robert B. Cohen LERNER, DAVID, LITTENBERG, KRUMHOLZ & MENTLIK, LLP Internal Address: Atty. Dkt.: Street Address: 600 South Avenue West	7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00 Authorized to be charged by credit card X Authorized to be charged to deposit account Enclosed None required (government interest not affecting title)
City: Westfield	8 Brownest Indonesting
State: NJ Zip; 07090	8. Payment Information a. Credit Card Last 4 Numbers
Phone Number: (908) 518-6316	Expiration Date
Fax Number: (908) 654-0415	b. Deposit Account Number 12-1095
Email Address:	Authorized User Name Robert B. Cohen
. Signature:	November 23, 2005 Date
Robert B. Cohen - 32,768	Total number of pages including cover sneet, attachments, and documents;
Name of Person Signing	11/29/2005 LMUELLER 00000006 121095
14866 - 1-DOC	01 FC:8021 (40.00 DA

PAGE 2/4 * RCVD AT 11/23/2005 5:27:47 PM [Eastern Standard Time] * SVR:USPTO-EFXRF-6/25 * DNIS:2733250 * CSID:19086547866 * DURATION (mm-ss):01-28

PATENT REEL: 017266 FRAME: 0139

S05P12Q1US00

Docket Number: SONYJP 3.0-465

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in INFORMATION PROCESSING DEVICE. METHOD. AND PROCESM

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged. I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents. Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filling of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patent; to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my anomey(s) of record in this application to insert the scrial number and filing date of this application in the spaces that follow: Serial Number: 11/225, 352 Filing Date: September 13, 2005

This assignment executed on the dates indicated below.

Tomoko TERAKADO		
Name of first or sole inventor	Execution date of U.S. Patent Application	
Kanagawa, Japan		
Residence of first or sole inventor		
Tempho Yorakadu	Date of this assignment	
Signature of first or sole inventor	Date of dits upsistance.	

PAGE 3/4 * RCVD AT 11/23/2005 5:27:47 PM [Eastern Standard Time] * SVR:USPTO-EFXRF-6/25 * DNIS:2733250 * CSID:19086547866 * DURATION (mm-ss):01-28

PATENT REEL: 017266 FRAME: 0140

S05P1201US00

Chieko KUSAKABE	
Name of second inventor	Execution date of U.S. Patent Application
Chiba, Japan	
Residence of second inventor	
Chieko Kusakabe Signature of second inventor	Nov. 11, 2005 Date of this assignment
Signature of second inventor	Date of this assignment
Kanako NAKAMURA	
Name of third inventor	Execution date of U.S. Patent Application
Tokyo, Japan	
Residence of third inventor	
Signature of third inventor	Nov. 9, 2005
Signature of third inventor	Date of this assignment
	•
Name of fourth inventor	Execution date of U.S. Patent Application
Residence of fourth inventor	
Signature of fourth inventor	Date of this assignment
Name of fifth inventor	Execution date of U.S. Patent Application
Residence of fifth inventor	
	Date of this assignment
Signature of fifth inventor	Date of the Long.

PAGE 4/4 * RCVD AT 11/23/2005 5:27:47 PM [Eastern Standard Time] * SVR:USPTO-EFXRF-6/25 * DNIS:2733250 * CSID:19086547866 * DURATION (mm-ss):01-28

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PATENT REEL: 017266 FRAME: 0141